



2818

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
Hsu, et al.

Serial No.: 09/739,139

Confirmation No.: 4854

Filed: December 18, 2000

For: Integrated Multi-Step Gap Fill  
And All Feature Planarization  
For Conductive Materials

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

Group Art Unit: 2818

Examiner: Q. Hoang

#6/Election  
3/21/02

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CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on <u>February 28, 2002</u> with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.	
<u>2/28/02</u> Date	<u>Keint 2 2002</u> Signature

**RESPONSE TO RESTRICTION REQUIREMENT DATED JANUARY 31, 2002**

In response to the Restriction Requirement dated January 31, 2002, having a shortened statutory period for response set to expire on February 28, 2002, Applicants elect claims 1-29, Group I, with traverse, and request reconsideration of the restriction requirement for the reasons discussed below. Although Applicant believes that no fee is due in conjunction with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/5614/CMP/CMP/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

**THE PENDING CLAIMS:**

1. An apparatus for depositing and planarizing a material on a substrate, comprising:
  - a) a partial enclosure defining a processing region and having a fluid inlet and a fluid outlet;